

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A method, comprising:
providing an RF antenna on an item; **[[and]]**
providing a RFID electronics module, the module electrically coupling the RFID electronics module to the RF antenna on the item after the RF antenna is provided on the item, the module being a chip mounted on a substrate and the coupling being a non-contact electrical coupling;
providing the RF antenna with a first set of electrically conductive pads;
providing the RFID electronics module with a second set of electrically conductive pads; and
aligning the first and second set of electrically conductive pads in a predetermined manner relative to each other when attaching the RFID electronics module to the item;

thereby providing an RFID module capability for the item.

2. (Original) The method of claim 1, wherein electrically coupling comprises attaching the RFID module to the item to provide an RFID function for the item.

3. (Canceled)

4. (Original) The method of claim 1, wherein the item includes an inside surface and an outside surface and further comprising providing the RF antenna on the inside surface of the item and attaching the RFID electronics module in an adjacent position to the outside surface of the item.

5. (Canceled)

6. (Original) The method of claim 1, further comprising providing a dielectric between the RF antenna and the RFID electronic module.

7. (Currently Amended) **[[A]]** The method of claim 1, further comprising,
~~applying an RF antenna directly to an item;~~
 providing **[[an]]** the RFID electronics module separate from the item and the
 RF antenna on the item ~~, the RFID electronics module including electronics that~~
~~provide an RFID capability when coupled to the RF antenna; and~~
 applying the RFID electronics module to the item after applying the RF
 antenna to the item ~~, whereby the RFID electronics module is a chip mounted on a~~
~~substrate that is electrically coupled to the RF antenna by a non-contact coupling.~~

8. (Original) The method of claim 7, further comprising:
 providing alignment features on the item and positioning the RFID electronics
 module on the item based on a location of the alignment features.

9. (Original) The method of claim 7, further comprising providing an adhesive on the RFID electronics module; and applying the RFID electronics module to the item by means of the adhesive.

10-11. (Canceled)

12. (Original) The method of claim 7, wherein applying the RF antenna to the item comprises printing the RF antenna on the item.

13. (Original) The method of claim 12 wherein the RF antenna is printed on the item using electrically conductive ink.

14. (Currently Amended) In combination, an item having at least one surface and an RF antenna applied to the surface; and an RFID electronics module separate from the item and from the RF antenna on the item, the RFID electronics module being a chip fixed to a substrate and including electronics which provide an RFID capability when coupled to the RF antenna, the RFID electronics module being applied to the item so as to be electrically coupled to the RF antenna and provide an RFID capability for the item, the RF antenna being coupled to the RFID electronics module by a non-contact coupling, and wherein the RF antenna and module have engaged electrically conductive pads aligned in a predetermined manner relative to each other when the RFID electronics module is applied to the items so as to provide the electrical coupling.

15. (Original) The combination of claim 14, further comprising an adhesive attaching the RFID electronics module to the item.

16. (Original) The combination of claim 14, further comprising a dielectric between the RFID electronics module and the RF antenna.

17. (Original) The combination of claim 14, wherein the RFID module is adapted to have its RFID capability modified if the RFID electronics module is tampered or removed from the item.